

Title (en)

Heat pump apparatus and operation control method of heat pump apparatus

Title (de)

Wärmepumpenvorrichtung und Betriebssteuerungsverfahren einer Wärmepumpenvorrichtungen

Title (fr)

Appareil de pompe à chaleur et procédé de contrôle de fonctionnement de l'appareil de pompe à chaleur

Publication

EP 2375187 A3 20141217 (EN)

Application

EP 11001441 A 20110221

Priority

JP 2010041386 A 20100226

Abstract (en)

[origin: EP2375187A2] The present invention aims to prevent a refrigerant at a low temperature from being sent to a load-side heat exchanger during a defrost operation. At a time of a heat radiating operation, a switching mechanism 2 is controlled such that the refrigerant from a compressor 1 flows to a load-side heat exchanger 3, thereby causing the heat exchanger 3 to operate as a heat radiator and causing at least one of heat-source-side heat exchangers 5a and 5b to operate as an evaporator. At a time of the defrost operation of removing frost at the heat exchanger 5a, the switching mechanism 2 is controlled such that the refrigerant from the compressor 1 flows to the heat exchangers 3 and 5a, thereby causing the heat exchangers 3 and 5a to operate as heat radiators and causing the heat exchanger 5b to operate as an evaporator.

IPC 8 full level

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CPC (source: EP)

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Citation (search report)

- [XI] EP 1801522 A2 20070627 - HU LUNG-TAN [CA]
- [XI] EP 0974792 A2 20000126 - EATON WILLIAMS GROUP LTD [GB]
- [XI] EP 0668474 A2 19950823 - SANYO ELECTRIC CO [JP]

Cited by

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Designated contracting state (EPC)

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